

AMENDMENTS TO THE CLAIMS

This Listing of Claims will replace all prior versions, listing, of claims in the specification.

LISTING OF CLAIMS:

Claim 1 (original) A method of separating a sapphire substrate and a thin film over said sapphire substrate, comprising the steps of:

providing a laser array over said sapphire substrate, said laser array emitting a plurality of laser lights and said plurality of laser lights at least partially penetrating said sapphire substrate and being absorbed by said thin film;

irradiating said thin film with said laser array through said sapphire substrate; and

separating said sapphire substrate and said thin film.

Claim 2 (original) The method according to Claim 1, wherein each of said plurality of laser lights has a wavelength of about 327 nm.

Claim 3 (original) The method according to Claim 1, wherein the step of irradiating said thin film is irradiating on an interface of said thin film with said sapphire substrate.

Claim 4 (original) The method according to Claim 1, wherein said laser array has a predetermined dimension.

Claim 5 (original) A method of separating a substrate and a thin film over said substrate, comprising the steps of:

providing a laser array over said substrate, said laser array emitting a plurality of laser lights and said plurality of laser lights at least partially penetrating said substrate and being absorbed by said thin film;

irradiating said thin film with said laser array through said substrate;
and

separating said substrate and said thin film.

Claim 6 (original) The method according to Claim 5, wherein the step of irradiating said thin film is irradiating an interface between said thin film and said substrate.

Claim 7 (original) The method according to Claim 5, wherein said laser array has a predetermined dimension.

Claims 8-9 (canceled).